

MIL-STD-883 - DRAFT SUMMARY OF CHANGES FOR REVISION K CHANGE NOTICE 2
(Draft Dated 21 October, 1016)

The following table summarizes the changes for MIL-STD-883 Rev. K Change Notice 2 (DRAFT)

REF No.	Method and Paragraph	Change	Source	Reason
1	1005.11: TABLE 1 Notes	corrected typos pressures to temperatures	DLA	Correction
2	1014.16: 1.1.c Notes	1/ To use this conversion, the free internal volume must be filled with 100% helium at 1 atm. 2/ For test conditions A1, A2, A5, CH1 and CH2, to convert an atm cm3/s (He) value to an atm cm3/s (Air) value, the atm cm3/s (He) value must	JC-12	Addition
3	1014.16: 2.1.2.3	will be greater than the minimum detection sensitivity capability of the mass spectrometer. shall be one-half order of magnitude greater than the minimum detectable leak rate of the mass spectrometer.	JC-12	Change / Clarification
4	1014.16: 2.4.4	detection sensitivity capability of the mass spectrometer. shall be one-half order of magnitude greater than the minimum detectable	JC-12	Change / Clarification
5	1014.16: 2.4.5.1	test times >45 must use TCF	JC-12	Change / Clarification
6	1014.16: 2.4.6.1	The failure criteria for Gross Leak, C4, is defined when one of the following two operational test characteristics is observed. 1. One instance is when the optical interferometer does not detect deflection of the lid as the chamber pressure was changed. 2. The second is when the lid initially deflects under pressure but quickly returns towards its unpressurized state due to the equalization of the internal device pressure caused by a gross leak.	JC-12	Change / Clarification
7	1014.16: 2.4.7.1	2.4.7.1 Method for retest without error code (manual fringing test). If the systems reports a device as "retest," the device is most likely a gross leaker. A "retest" response implies collective data is insufficient to distinguish a gross leaker from a non leaking device. Therefore, manual fringing method must be performed in accordance with the equipment manufacturer's defined procedures. This additional testing shall be documented and records shall be retained for traceability.	JC-12	Addition
8	1014.16: 2.4.7.2	2.4.7.2 Method for retest with error code. If the system reports a device as "retest" with an error code, a retest may be performed in accordance with the equipment manufacturer's defined procedure. This procedure must address the proper wait time necessary to ensure the internal package pressure has equalized with the outside pressure before the test is repeated. This proper wait time shall be determined through repeated testing of a fine leaking package, and the data shall be available to the acquiring or qualifying activity upon request. This additional testing shall be documented and records shall be retained for traceability.	JC-12	Addition
9	1014.16: 2.8.2.1	leak rate standards shall be recalibrated at least every five years once per year.	JC-12	Change
10	1014.16: 2.8.3.3.3	Clarified thermal bake out	DLA	Change
11	1014.16: TABLE V	corrected typo Equivalent "L" Value for >0.40<0.50	DLA	Correction
12	1015.12: TABLE 1 Notes	corrected typos pressures to temperatures	DLA	Correction
13	1018.9	2.1.2 Quarterly calibration for other gases. Calibration Quarterly calibration	JC-13	Clarification
14	2003.13: 3.1	diethylammonium diethylamine	JC-13 TG	Correction
15	2003.13: 4.4	4.4 Solderability test. The test is divided into two methods: Dip and Look and BGA/CGA Surface Mount Simulation method shall be as follows. Test A – For Dip and Look Test Test B – For Ball Grid Array (BGA) Surface Mount Simulation Test Test C – For Column Grid Array (CGA) Surface Mount Simulation Test	JC-13 TG	Change / Clarification
16	2009.13: 3.3.6.b	i. Solder column base is misaligned such that the column is not within the perimeter of the pad. ii. Solder column tip misalignment that does not meet drawing requirements (typically < 100 µm). iii. Solder ball misalignment that does not meet drawing requirements.	JC-13 TG	Change / Clarification
17	2009.13: 3.3.6.i	Solder fillet height which is less than half the column diameter for more than 25% of the column circumference.	JC-13 TG	Clarification
18	2009.13: 3.3.6.o	Pad dewetting/non-wetting greater than 5% of the pad surface area.	JC-13 TG	Clarification

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19	2012.10:	Complete re-write	JC-13 TG	Re-write
20	2017.12: 3.1.2.1.c	End terminated elements with less than 50% attach adhesive visible on each side termination and or less than 75% attach visible on the end of the termination. (see figs. 2017-5, 2017-6, and 2017-7).	DLA	Change / Clarification
21	3013.2: 3.3.2	pulse amplitude shall be equal to VOH (max); shall be superimposed on a dc level equal to VOH (min);	DLA	Correction
22	3019.2: 1.2	Corrected symbols for pi (π)	DLA	Correction
23	4003.2: 3.3.1	Corrected symbols for delta (Δ)	DLA	Correction
24	4006.2: 3.1	Corrected equation for Rg prime (R_G')	DLA	Correction